

DATA SHEET

For a complete data sheet, please also download:

- The IC06 74HC/HCT/HCU/HCMOS Logic Family Specifications
- The IC06 74HC/HCT/HCU/HCMOS Logic Package Information
- The IC06 74HC/HCT/HCU/HCMOS Logic Package Outlines

74HC/HCT257

Quad 2-input multiplexer; 3-state

Product specification
Supersedes data of September 1993
File under Integrated Circuits, IC06

1998 Sep 30

Quad 2-input multiplexer; 3-state

74HC/HCT257

FEATURES

- Non-inverting data path
- 3-state outputs interface directly with system bus
- Output capability: bus driver
- I_{CC} category: MSI

GENERAL DESCRIPTION

The 74HC/HCT257 are high-speed Si-gate CMOS devices and are pin compatible with low power Schottky TTL (LSTTL). They are specified in compliance with JEDEC standard no. 7A.

The 74HC/HCT257 have four identical 2-input multiplexers with 3-state outputs, which select 4 bits of data from two sources and are controlled by a common data select input (S).

The data inputs from source 0 (1I₀ to 4I₀) are selected when input S is LOW and the data inputs from source 1 (1I₁ to 4I₁) are selected when S is HIGH. Data appears at the outputs (1Y to 4Y) in true (non-inverting) form from the selected inputs.

The “257” is the logic implementation of a 4-pole, 2-position switch, where the position of the switch is determined by the logic levels applied to S. The outputs are forced to a high impedance OFF-state when \overline{OE} is HIGH.

The logic equations for the outputs are:

$$1Y = \overline{OE} \cdot (1I_1 \cdot S + 1I_0 \cdot \overline{S})$$

$$2Y = \overline{OE} \cdot (2I_1 \cdot S + 2I_0 \cdot \overline{S})$$

$$3Y = \overline{OE} \cdot (3I_1 \cdot S + 3I_0 \cdot \overline{S})$$

$$4Y = \overline{OE} \cdot (4I_1 \cdot S + 4I_0 \cdot \overline{S})$$

The “257” is identical to the “258” but has non-inverting (true) outputs.

QUICK REFERENCE DATA

GND = 0 V; T_{amb} = 25 °C; t_r = t_f = 6 ns

| SYMBOL | PARAMETER | CONDITIONS | TYPICAL | | UNIT |
|-------------------------------------|---|---|---------|-----|------|
| | | | HC | HCT | |
| t _{PHL} / t _{PLH} | propagation delay | C _L = 15 pF; V _{CC} = 5 V | | | |
| | nI ₀ , nI ₁ to nY | | 11 | 13 | ns |
| | S to nY | | 14 | 17 | ns |
| C _I | input capacitance | | 3.5 | 3.5 | pF |
| C _{PD} | power dissipation capacitance per multiplexer | notes 1 and 2 | 45 | 45 | pF |

Notes

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW):

$$P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz

f_o = output frequency in MHz

∑ (C_L × V_{CC}² × f_o) = sum of outputs

C_L = output load capacitance in pF

V_{CC} = supply voltage in V

2. For HC the condition is V_I = GND to V_{CC}

For HCT the condition is V_I = GND to V_{CC} – 1.5 V

Quad 2-input multiplexer; 3-state

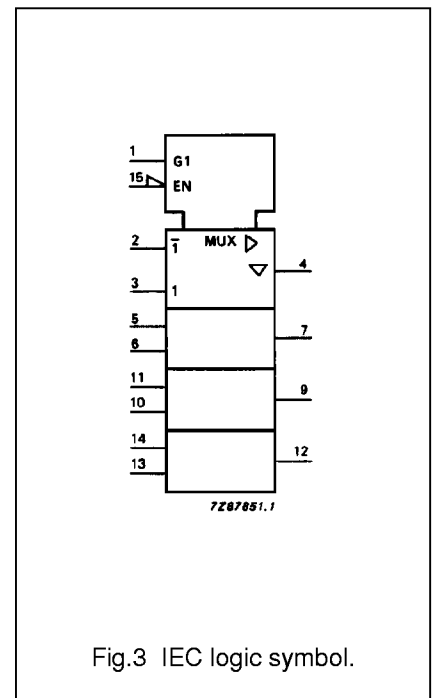
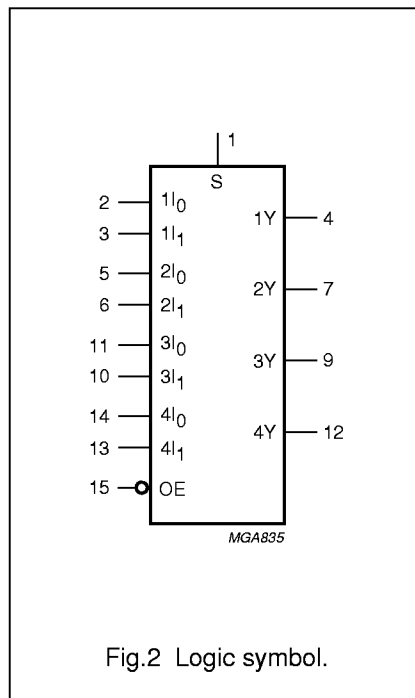
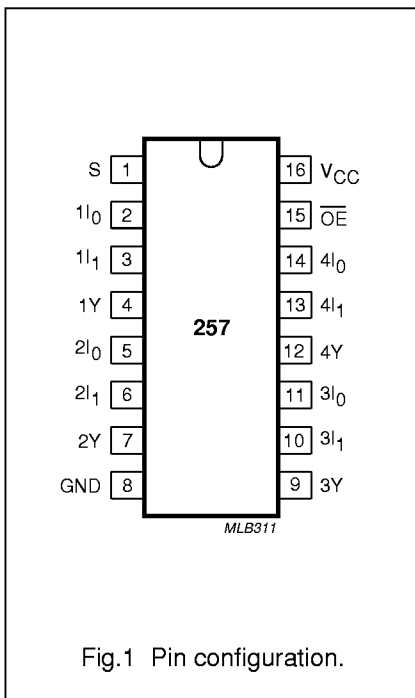
74HC/HCT257

ORDERING INFORMATION

| TYPE NUMBER | PACKAGE | | |
|--------------------------|---------|--|----------|
| | NAME | DESCRIPTION | VERSION |
| 74HC257N; 74HCT257N | DIP16 | plastic dual in-line package; 16 leads (300 mil); long body | SOT38-1 |
| 74HC257D; 74HCT257D | SO16 | plastic small outline package; 16 leads; body width 3.9 mm | SOT109-1 |
| 74HC257DB; 74HCT257DB | SSOP16 | plastic shrink small outline package; 16 leads; body width 5.3 mm | SOT338-1 |
| 74HC257PW; 74HCT257PW | TSSOP16 | plastic thin shrink small outline package; 16 leads; body width 4.4 mm | SOT403-1 |

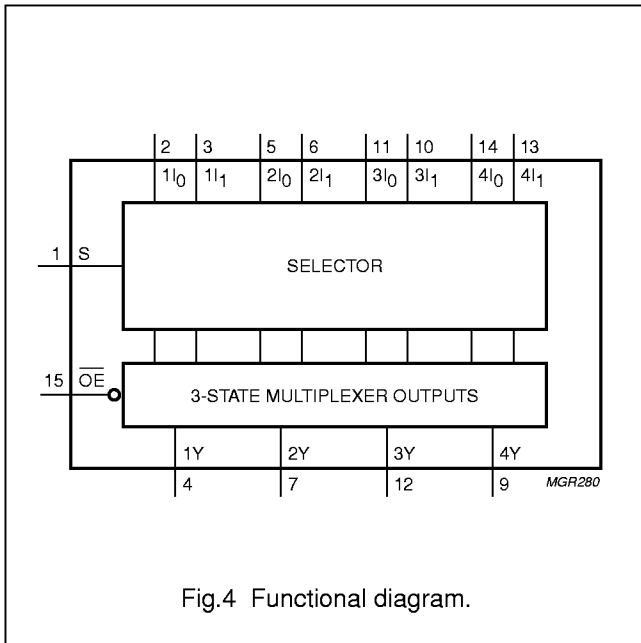
PIN DESCRIPTION

| PIN NO. | SYMBOL | NAME AND FUNCTION |
|--------------|------------------------------------|--|
| 1 | S | common data select input |
| 2, 5, 11, 14 | 1I ₀ to 4I ₀ | data inputs from source 0 |
| 3, 6, 10, 13 | 1I ₁ to 4I ₁ | data inputs from source 1 |
| 4, 7, 9, 12 | 1Y to 4Y | 3-state multiplexer outputs |
| 8 | GND | ground (0 V) |
| 15 | \overline{OE} | 3-state output enable input (active LOW) |
| 16 | V _{CC} | positive supply voltage |



Quad 2-input multiplexer; 3-state

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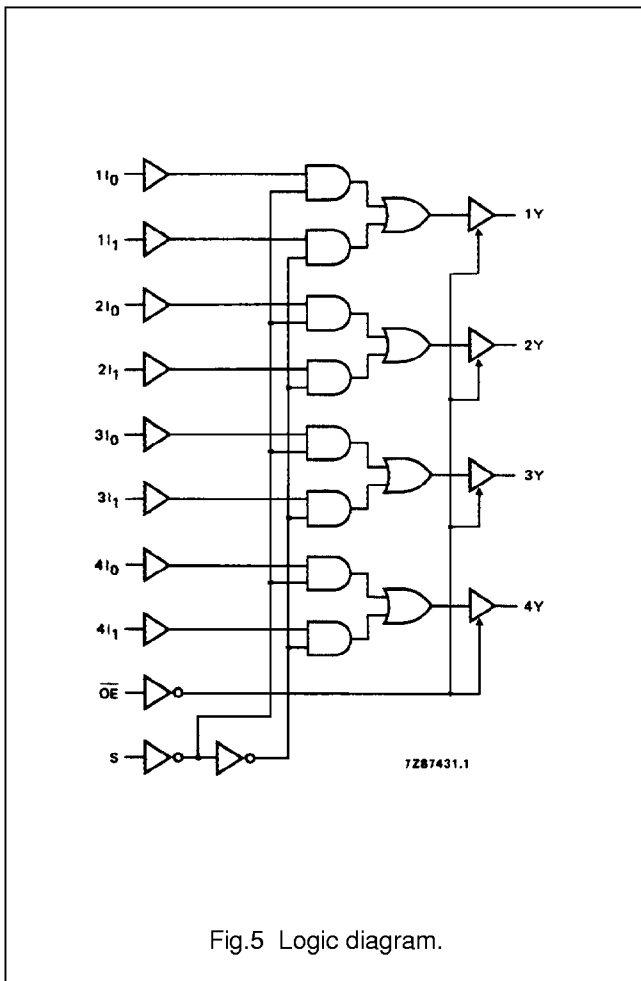


FUNCTION TABLE

| INPUTS | | | | OUTPUT |
|-----------------|---|--------|--------|--------|
| \overline{OE} | S | nI_0 | nI_1 | nY |
| H | X | X | X | Z |
| L | H | X | L | L |
| L | H | X | H | H |
| L | L | L | X | L |
| L | L | H | X | H |

Notes

1. H = HIGH voltage level
 L = LOW voltage level
 X = don't care
 Z = high impedance OFF-state



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DC CHARACTERISTICS FOR 74HC

For the DC characteristics see "74HC/HCT/HCU/HCMOS Logic Family Specifications".

Output capability: bus driver

I_{CC} category: MSI

AC CHARACTERISTICS FOR 74HC

GND = 0 V; t_r = t_f = 6 ns; C_L = 50 pF

| SYMBOL | PARAMETER | T _{amb} (°C) | | | | | | UNIT | TEST CONDITIONS | | |
|-------------------------------------|--|-----------------------|----------------|-----------------|------------|-----------------|-------------|-----------------|------------------------|-------------------|-------|
| | | 74HC | | | | | | | V _{CC} (V) | WAVEFORMS | |
| | | +25 | | | -40 to +85 | | -40 to +125 | | | | |
| | | min. | typ. | max. | min. | max. | min. | | | | max. |
| t _{PHL} / t _{PLH} | propagation delay nI ₀ to nY; nI ₁ to nY | | 36 13 10 | 110 22 19 | | 140 28 24 | | 165 33 28 | ns | 2.0 4.5 6.0 | Fig.6 |
| t _{PHL} / t _{PLH} | propagation delay S to nY | | 47 17 14 | 150 30 26 | | 190 38 33 | | 225 45 38 | ns | 2.0 4.5 6.0 | Fig.6 |
| t _{PZH} / t _{PZL} | 3-state output enable time \overline{OE} to nY | | 33 12 10 | 150 30 26 | | 190 38 33 | | 225 45 38 | ns | 2.0 4.5 6.0 | Fig.7 |
| t _{PHZ} / t _{PLZ} | 3-state output disable time \overline{OE} to nY | | 41 15 12 | 150 30 26 | | 190 38 33 | | 225 45 38 | ns | 2.0 4.5 6.0 | Fig.7 |
| t _{THL} / t _{TLH} | output transition time | | 14 5 4 | 60 12 10 | | 75 15 13 | | 90 18 15 | ns | 2.0 4.5 6.0 | Fig.6 |

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DC CHARACTERISTICS FOR 74HCT

For the DC characteristics see “74HC/HCT/HCU/HCMOS Logic Family Specifications”.

Output capability: bus driver

I_{CC} category: MSI

Note to HCT types

The value of additional quiescent supply current (ΔI_{CC}) for a unit load of 1 is given in the family specifications. To determine ΔI_{CC} per input, multiply this value by the unit load coefficient shown in the table below.

| INPUT | UNIT LOAD COEFFICIENT |
|-----------------|-----------------------|
| nI ₀ | 0.40 |
| nI ₁ | 0.40 |
| \overline{OE} | 1.35 |
| S | 0.70 |

AC CHARACTERISTICS FOR 74HCT

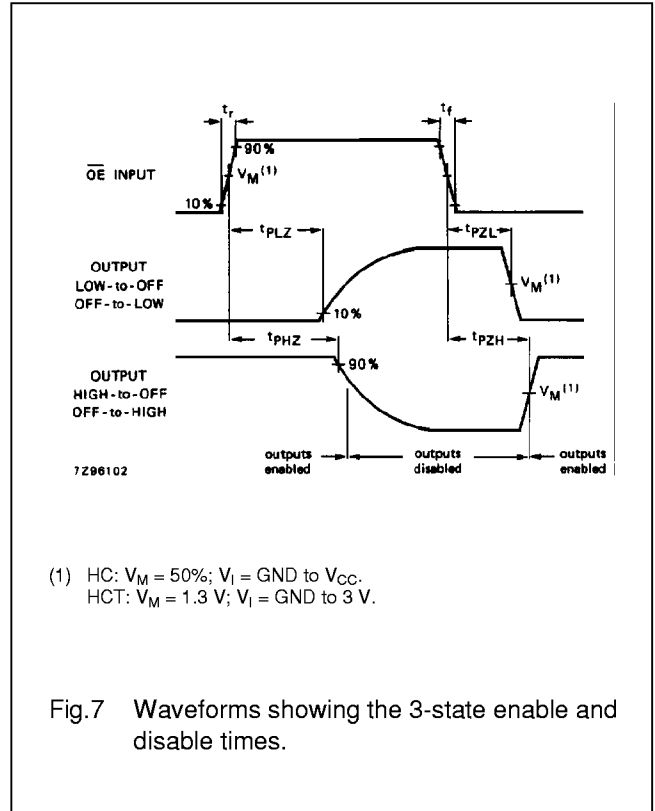
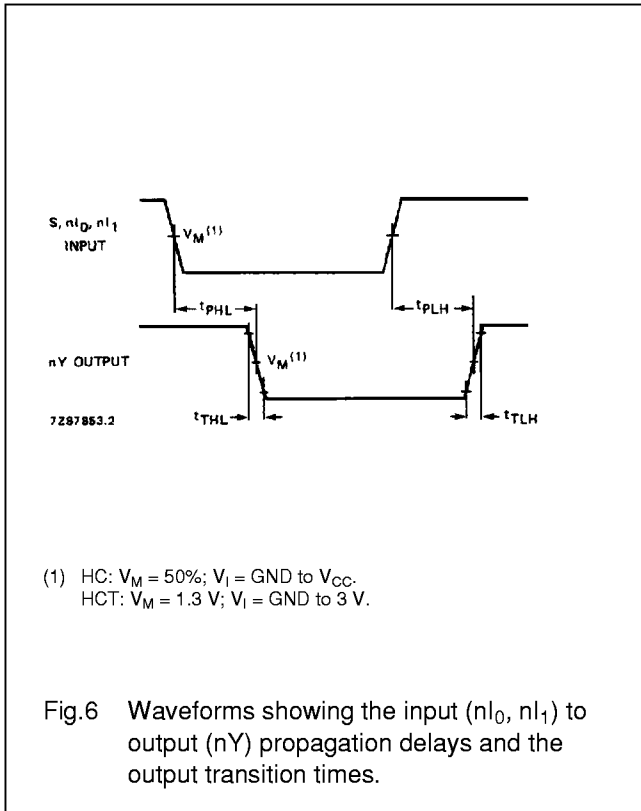
GND = 0 V; t_r = t_f = 6 ns; C_L = 50 pF

| SYMBOL | PARAMETER | T _{amb} (°C) | | | | | | | | UNIT | TEST CONDITIONS | |
|-------------------------------------|---|-----------------------|------|------|------------|------|-------------|------|----|------|------------------------|-----------|
| | | 74HCT | | | | | | | | | V _{CC} (V) | WAVEFORMS |
| | | +25 | | | -40 to +85 | | -40 to +125 | | | | | |
| | | min. | typ. | max. | min. | max. | min. | max. | | | | |
| t _{PHL} / t _{PLH} | propagation delay nI ₀ to nY nI ₁ to nY | | 16 | 30 | | 38 | | 45 | ns | 4.5 | Fig.6 | |
| t _{PHL} / t _{PLH} | propagation delay S to nY | | 20 | 35 | | 44 | | 53 | ns | 4.5 | Fig.6 | |
| t _{PZH} / t _{PZL} | 3-state output enable time \overline{OE} to nY | | 15 | 30 | | 38 | | 45 | ns | 4.5 | Fig.7 | |
| t _{PHZ} / t _{PLZ} | 3-state output disable time \overline{OE} to nY | | 16 | 30 | | 38 | | 45 | ns | 4.5 | Fig.7 | |
| t _{THL} / t _{TLH} | output transition time | | 5 | 12 | | 15 | | 18 | ns | 4.5 | Fig.6 | |

Quad 2-input multiplexer; 3-state

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AC WAVEFORMS



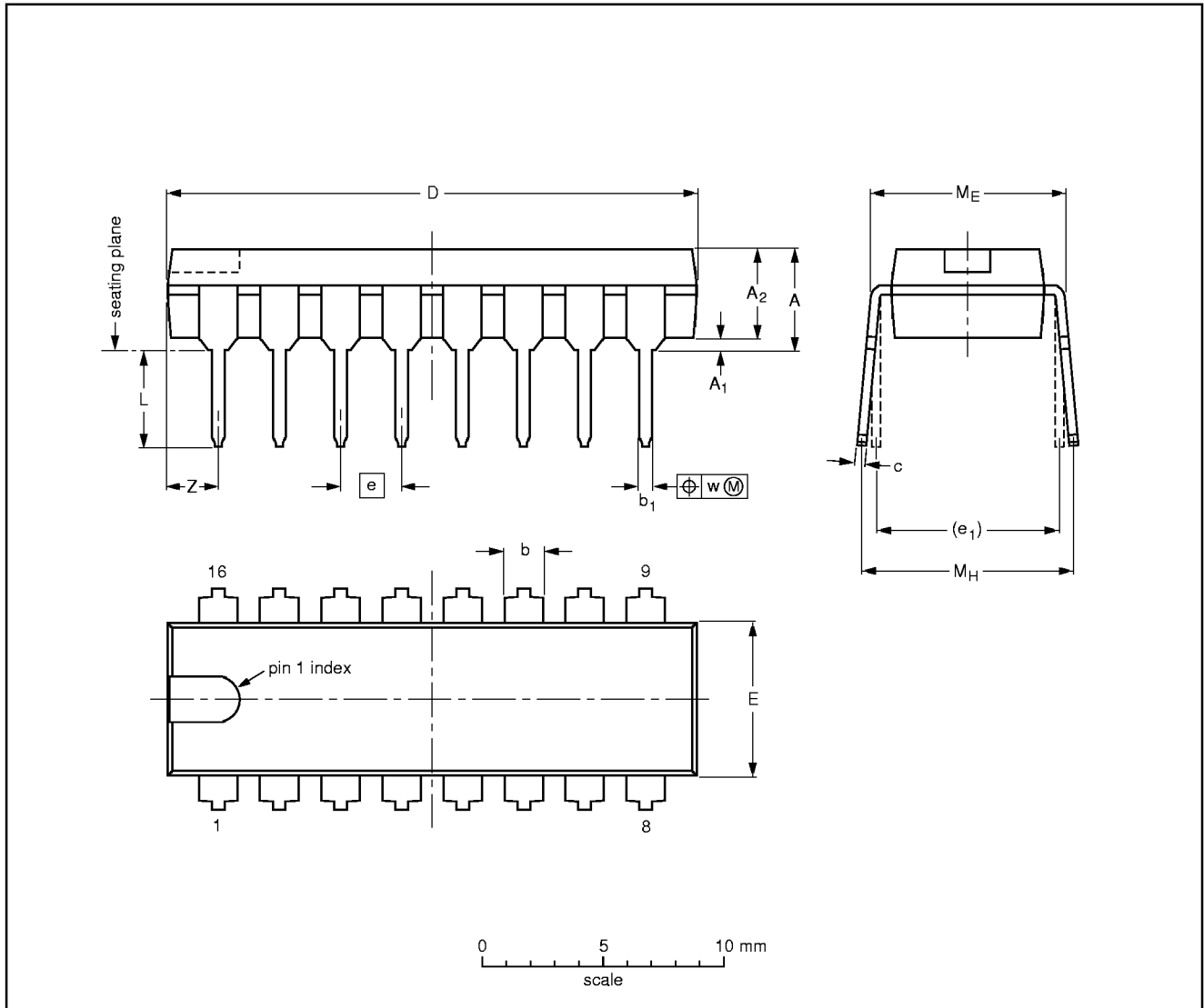
Quad 2-input multiplexer; 3-state

74HC/HCT257

PACKAGE OUTLINES

DIP16: plastic dual in-line package; 16 leads (300 mil); long body

SOT38-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

| UNIT | A max. | A ₁ min. | A ₂ max. | b | b ₁ | c | D ⁽¹⁾ | E ⁽¹⁾ | e | e ₁ | L | M _E | M _H | w | Z ⁽¹⁾ max. |
|--------|--------|---------------------|---------------------|----------------|----------------|----------------|------------------|------------------|------|----------------|--------------|----------------|----------------|-------|-----------------------|
| mm | 4.7 | 0.51 | 3.7 | 1.40 1.14 | 0.53 0.38 | 0.32 0.23 | 21.8 21.4 | 6.48 6.20 | 2.54 | 7.62 | 3.9 3.4 | 8.25 7.80 | 9.5 8.3 | 0.254 | 2.2 |
| inches | 0.19 | 0.020 | 0.15 | 0.055 0.045 | 0.021 0.015 | 0.013 0.009 | 0.86 0.84 | 0.26 0.24 | 0.10 | 0.30 | 0.15 0.13 | 0.32 0.31 | 0.37 0.33 | 0.01 | 0.087 |

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

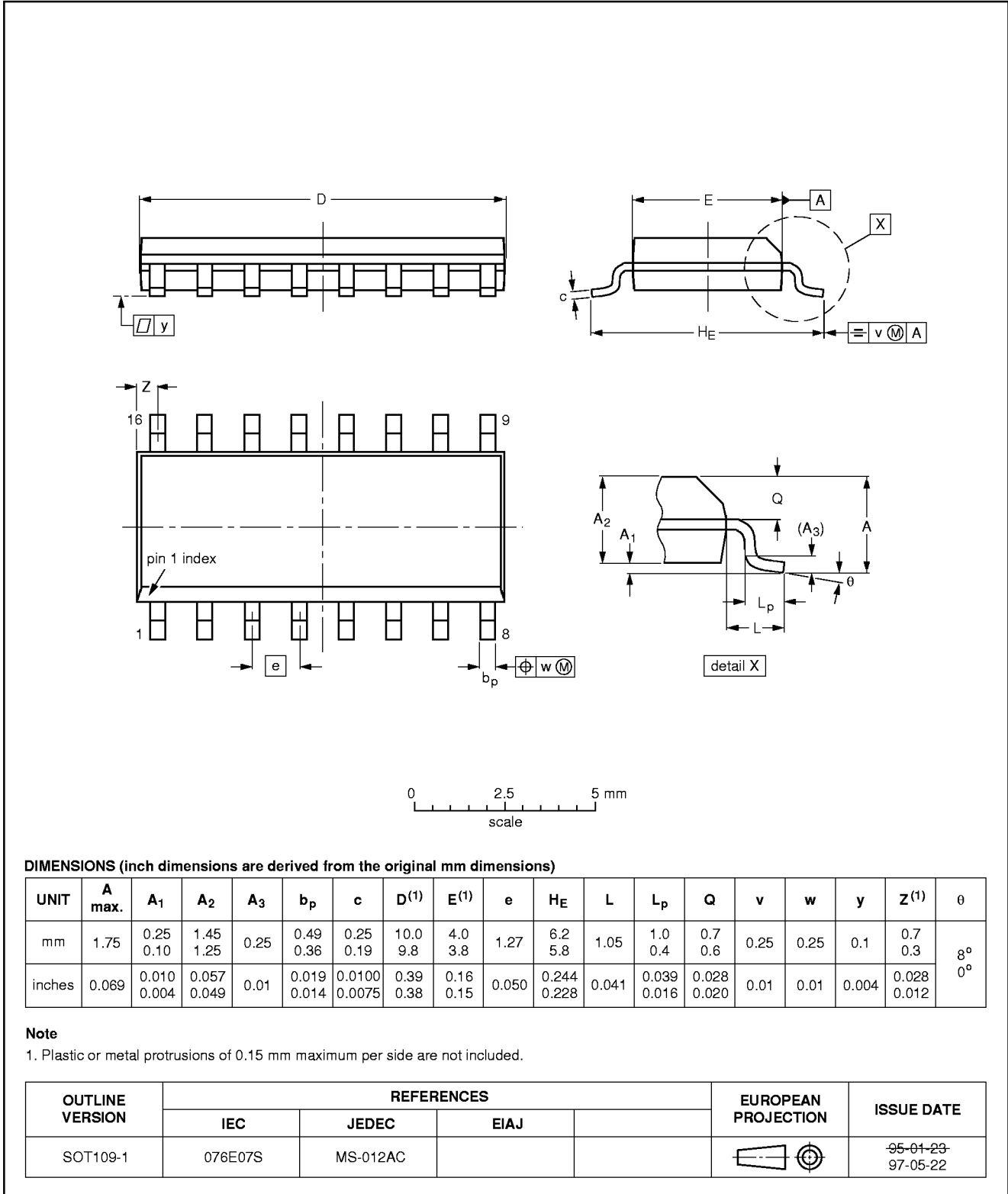
| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|----------|------|--|---------------------|----------------------|
| | IEC | JEDEC | EIAJ | | | |
| SOT38-1 | 050G09 | MO-001AE | | | | 92-10-02 95-01-19 |

Quad 2-input multiplexer; 3-state

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SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

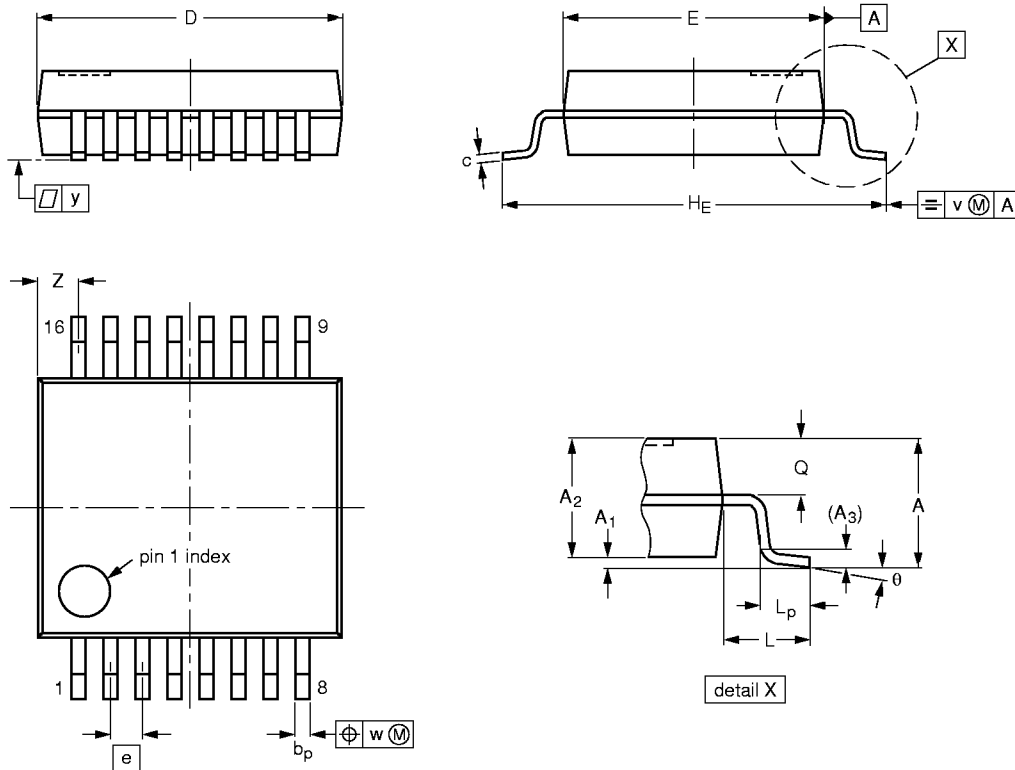


Quad 2-input multiplexer; 3-state

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SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1



DIMENSIONS (mm are the original dimensions)

| UNIT | A max. | A ₁ | A ₂ | A ₃ | b _p | c | D ⁽¹⁾ | E ⁽¹⁾ | e | H _E | L | L _p | Q | v | w | y | z ⁽¹⁾ | θ |
|------|--------|----------------|----------------|----------------|----------------|--------------|------------------|------------------|------|----------------|------|----------------|------------|-----|------|-----|------------------|----------|
| mm | 2.0 | 0.21 0.05 | 1.80 1.65 | 0.25 | 0.38 0.25 | 0.20 0.09 | 6.4 6.0 | 5.4 5.2 | 0.65 | 7.9 7.6 | 1.25 | 1.03 0.63 | 0.9 0.7 | 0.2 | 0.13 | 0.1 | 1.00 0.55 | 8° 0° |

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

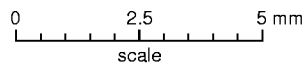
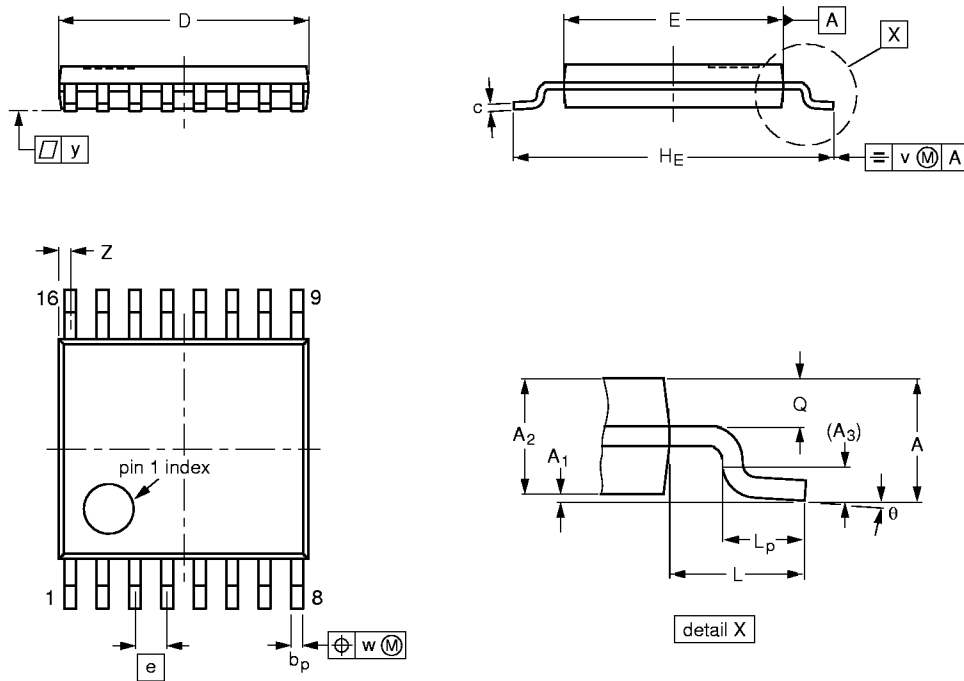
| OUTLINE VERSION | REFERENCES | | | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|----------|------|---------------------|----------------------|
| | IEC | JEDEC | EIAJ | | |
| SOT338-1 | | MO-150AC | | | 94-01-14 95-02-04 |

Quad 2-input multiplexer; 3-state

74HC/HCT257

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1



DIMENSIONS (mm are the original dimensions)

| UNIT | A _{max.} | A ₁ | A ₂ | A ₃ | b _p | c | D ⁽¹⁾ | E ⁽²⁾ | e | H _E | L | L _p | Q | v | w | y | Z ⁽¹⁾ | θ |
|------|-------------------|----------------|----------------|----------------|----------------|------------|------------------|------------------|------|----------------|-----|----------------|------------|-----|------|-----|------------------|----------|
| mm | 1.10 | 0.15 0.05 | 0.95 0.80 | 0.25 | 0.30 0.19 | 0.2 0.1 | 5.1 4.9 | 4.5 4.3 | 0.65 | 6.6 6.2 | 1.0 | 0.75 0.50 | 0.4 0.3 | 0.2 | 0.13 | 0.1 | 0.40 0.06 | 8° 0° |

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|--------|------|--|---------------------|-----------------------|
| | IEC | JEDEC | EIAJ | | | |
| SOT403-1 | | MO-153 | | | | 94-07-12- 95-04-04 |

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SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (order code 9398 652 90011).

DIP

SOLDERING BY DIPPING OR BY WAVE

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg\ max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

REPAIRING SOLDERED JOINTS

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

SO, SSOP and TSSOP

REFLOW SOLDERING

Reflow soldering techniques are suitable for all SO, SSOP and TSSOP packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method.

Typical reflow temperatures range from 215 to 250 °C. Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

WAVE SOLDERING

Wave soldering can be used for all SO packages. Wave soldering is **not** recommended for SSOP and TSSOP packages, because of the likelihood of solder bridging due to closely-spaced leads and the possibility of incomplete solder penetration in multi-lead devices.

If wave soldering is used - **and cannot be avoided for SSOP and TSSOP packages** - the following conditions must be observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow and must incorporate solder thieves at the downstream end.

Even with these conditions:

- **Only consider wave soldering SSOP packages that have a body width of 4.4 mm, that is SSOP16 (SOT369-1) or SSOP20 (SOT266-1).**
- **Do not consider wave soldering TSSOP packages with 48 leads or more, that is TSSOP48 (SOT362-1) and TSSOP56 (SOT364-1).**

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

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REPAIRING SOLDERED JOINTS

Fix the component by first soldering two diagonally- opposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

DEFINITIONS

| | |
|---|---|
| Data sheet status | |
| Objective specification | This data sheet contains target or goal specifications for product development. |
| Preliminary specification | This data sheet contains preliminary data; supplementary data may be published later. |
| Product specification | This data sheet contains final product specifications. |
| Limiting values | |
| Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability. | |
| Application information | |
| Where application information is given, it is advisory and does not form part of the specification. | |

LIFE SUPPORT APPLICATIONS

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